

RoHS

HALOGEN FREE

SM3335PSQA-VB Datasheet P-Channel 30 V (D-S) MOSFET

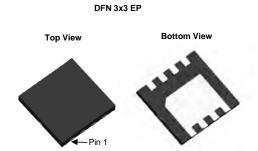
V_{DS}		-30	V
$R_{DS(on),typ}$	V _{GS} =10V	11	mΩ
$R_{DS(on),typ}$	V _{GS} =4.5V	18	mΩ
ID	-45	Α	

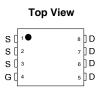
FEATURES

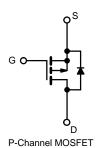
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- Low Thermal Resistance Package with Small Size and Low 1.07 mm
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- · Load Switch
- Adaptor Switch
- Notebook PC







Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C		- 45	
Continuous Proin Current /T = 150 °C)	T _C = 70 °C		- 30	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 14.4 ^{a, b}	
	T _A = 70 °C		- 11.5 ^{a, b}	
Pulsed Drain Current		I _{DM}	- 60	A
Continuous Source-Drain Diode Current	T _C = 25 °C		- 35 ^e	
Continuous Source-Drain Diode Current	T _A = 25 °C		- 3.2 ^{a, b}	
Avalanche Current	L = 0.1 mH	I _{AS}	- 25	
Single-Pulse Avalanche Energy	L=0.11IIII	E _{AS}	31.25	mJ
	T _C = 25 °C		52	
Mayimum Dawar Dissination	T _C = 70 °C	P _D	43	w
Maximum Power Dissipation	T _A = 25 °C	LD	3.8 ^{a, b}	VV
	T _A = 70 °C		2.4 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 50 to 150	°C	
Soldering Recommendations (Peak Temperature) ^{c, o}		260		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c.Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- d.Package limited.
- e.Based on T $_{C}$ = 25 $^{\circ}C$



THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	26	33	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.9	2.4	C/ VV

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under Steady State conditions is 81 °C/W.

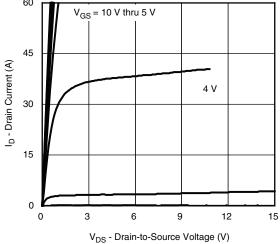
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		<u>, </u>					
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 20		m\//°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- Ι _D = - 250 μΑ		5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.5		- 2.8	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtara Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			-1		
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α	
Durin Course Co Oleta Basistana a	B	V _{GS} = - 10 V, I _D = - 14.4 A		11		mO	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 11.5 A		18		mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 14.4 A		37		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2000		pF	
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		385			
Reverse Transfer Capacitance	C _{rss}			322			
Total Cata Charge	otal Gate Charge $Q_g = V_{DS} = -15 \text{ V, V}_0$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -14.4 \text{ A}$			15	5	
Total Gate Charge					14	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -14.4 \text{ A}$			7		
Gate-Drain Charge	Q_{gd}				9		
Gate Resistance	R_{g}	f = 1 MHz	0.4	1.8	3.6	Ω	
Turn-On Delay Time	t _{d(on)}			50	75		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_L = 1.5 \Omega$		43	65		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		30	45		
Fall Time	t _f			14	21		
Turn-On Delay Time	t _{d(on)}			14	21	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		9	18		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		36	54		
Fall Time	t _f			10	20		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 35 ^e	Α	
Pulse Diode Forward Current ^a	I _{SM}				- 60] ^	
Body Diode Voltage	V _{SD}	I _F = - 10 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			31	47	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	- I _F = - 10 A, dl/dt = 100 A/μs, T _{.J} = 25 °C		30	45	nC	
Reverse Recovery Fall Time	t _a	$\frac{1}{1}$ $\frac{1}$		15		no	
Reverse Recovery Rise Time	t _b	1		16		ns	

Notes:

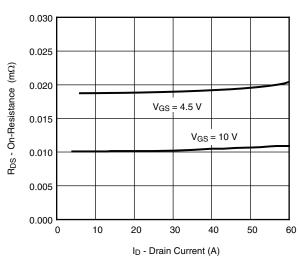
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

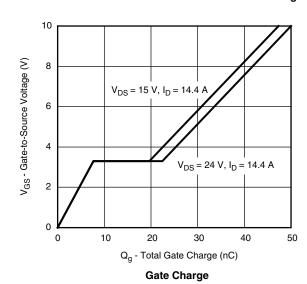






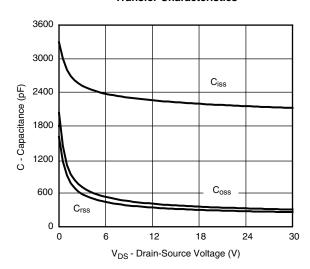


On-Resistance vs. Drain Current and Gate Voltage

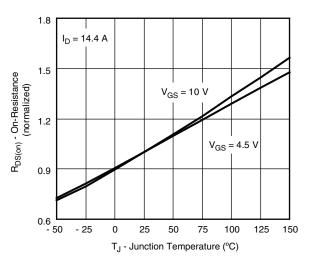


1.2 0.9 I_D - Drain Current (A) 125 °C 0.6 25 °C 0.3 - 55 °C 0.0 0 4 V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics

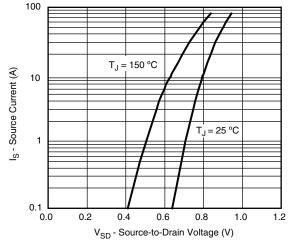


Capacitance

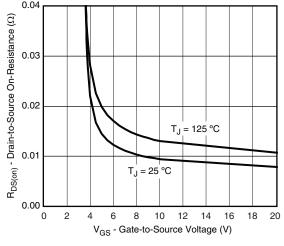


On-Resistance vs. Junction Temperature

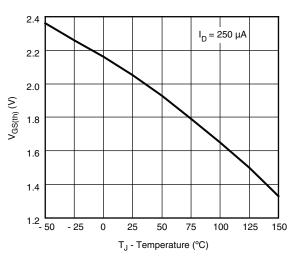




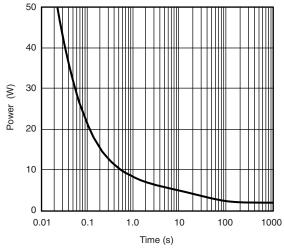
Source-Drain Diode Forward Voltage



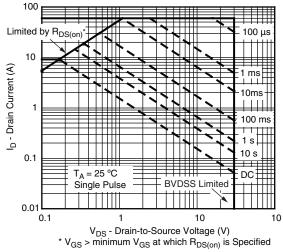
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



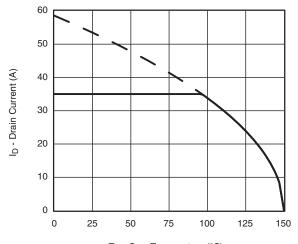
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

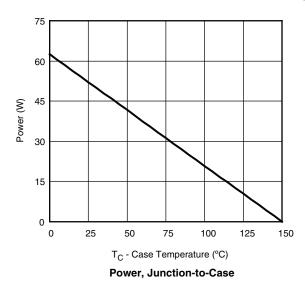
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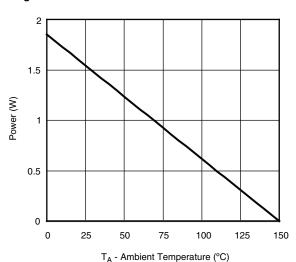




 $T_{\mbox{\scriptsize C}}$ - CaseTemperature (°C)

Current Derating*

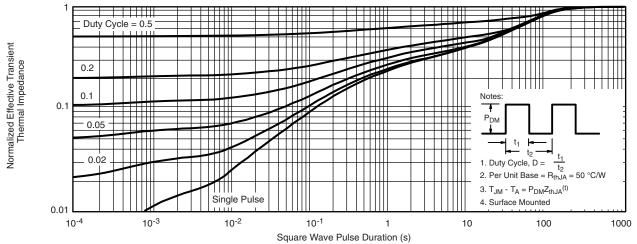




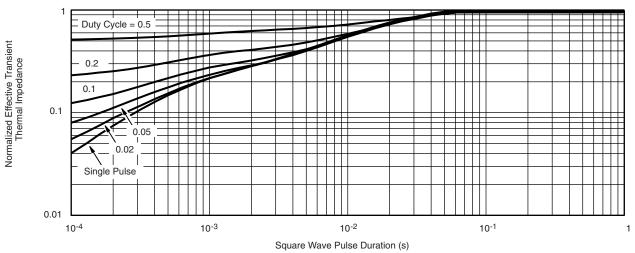
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient

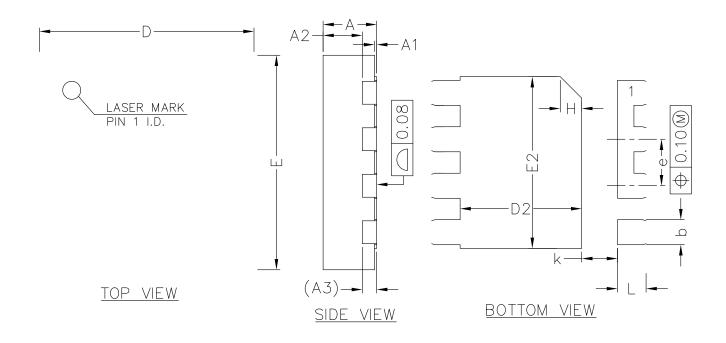


Normalized Thermal Transient Impedance, Junction-to-Case

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COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX		
А	0.70	0.75	0.80		
A1	0.00	0.02	0.05		
A2	0.50	0.55	0.60		
А3	0.20REF				
b	0.30	0.35	0.40		
D	2.90	3.00	3.10		
Е	2.90	3.00	3.10		
D2	1.60	1.70	1.80		
E2	2.30	2.40	2.50		
е	0.55	0.65	0.75		
K	0.40	0.50	0.60		
L	0.35	0.40	0.45		



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